MARKING



TinyLogic UHS Two-Input OR Gate

NC7SZ32

Description

The NC7SZ32 is a single two-input OR gate from **onsemi's** Ultra–High Speed (UHS) series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra–high speed with high output drive while maintaining low static power dissipation over a broad $V_{\rm CC}$ operating range. The device is specified to operate over the 1.65 V to 5.5 V $V_{\rm CC}$ operating range. The inputs and output are high impedance when $V_{\rm CC}$ is 0 V. Inputs tolerate voltages up to 5.5 V, independent of $V_{\rm CC}$ operating voltage.

Features

- Ultra-High Speed: $t_{PD} = 2.4 \text{ ns}$ (Typical) into 50 pF at 5 V V_{CC}
- High Output Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Matches Performance of LCX Operated at 3.3 V V_{CC}
- Power Down High-Impedance Inputs / Outputs
- Over-Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise / EMI Reduction Circuitry
- Ultra-Small MicroPakTM Packages
- Space-Saving SOT23-5, SC-74A and SC-88A Packages
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

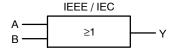


Figure 1. Logic Symbol

DIAGRAMS HHKK SIP6 CASE 127EB XYZ Pin 1 UDFN6 **HHKK** CASE 517DP XYZ SC-74A 7Z32 M• CASE 318BQ SOT23-5 CASE 527AH SC-88A Z32 M• CASE 419A-02

HH, 7Z32, Z32 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code
XY = 2-Digit Date Code Format
Z = Assembly Plant Code
An approximation of the Code

M = Date Code= Pb-Free Package

(Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

Pin Configurations

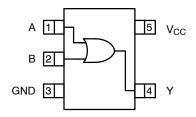


Figure 2. SOT23-5, SC-88A and SC-74A (Top View)

A 1 6 V_{CC} B 2 5 NC GND 3 4 Y

Figure 3. MicroPak (Top Through View)

PIN DEFINITIONS

Pin # SC-88A / SC74A/			
SOT23-5	Pin # MicroPak	Name	Description
1	1	Α	Input
2	2	В	Input
3	3	GND	Ground
4	4	Υ	Output
5	6	V _{CC}	Supply Voltage
	5	NC	No Connect

FUNCTION TABLE (Y = A + B)

Inp	Output	
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

H = HIGH Logic Level L = LOW Logic Level

ABSOLUTE MAXIMUM RATINGS

Symbol	Parame	Parameter		Max	Unit
V _{CC}	Supply Voltage		-0.5	6.5	V
V _{IN}	DC Input Voltage		-0.5	6.5	V
V _{OUT}	DC Output Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	-	-50	mA
l _{ok}	DC Output Diode Current	V _{OUT} < 0 V	-	-50	mA
l _{out}	DC Output Current		-	±50	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current		-	±50	mA
T _{STG}	Storage Temperature Range		-65	+150	°C
T_J	Junction Temperature Under Bias		-	+150	°C
T_L	Junction Lead Temperature (Solde	ering, 10 Seconds)	-	+260	°C
P_{D}	Power Dissipation in Still Air	SC-74A / SOT23-5	-	390	mW
		SC-88A	-	332	
		MicroPak-6	-	812	
		MicroPak2™-6	-	812	
ESD	Human Body Model, JEDEC: JESD22-A114		-	4000	V
	Charge Device Model, JEDEC: JE	SD22-C101	-	2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.50	V
	Supply Voltage Data Retention		1.50	5.50	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Times	V _{CC} = 1.8 V, 2.5 V ±0.2 V	0	20	ns/V
		V _{CC} = 3.3 V ±0.3 V	0	10	
		V _{CC} = 5.0 V ±0.5 V	0	5	
$\theta_{\sf JA}$	Thermal Resistance	SC-74A / SOT23-5	-	320	°C/W
		SC-88A	-	377	
		MicroPak-6	-	154	
		MicroPak2-6	-	154	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

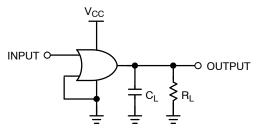
DC ELECTICAL CHARACTERISTICS

				T,	<u>1</u> = +25°	°C	T _A = -40	to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage	1.65 to 1.95		0.65 V _{CC}	-	-	0.65 V _{CC}	-	V
		2.30 to 5.50		0.70 V _{CC}	_	-	0.70 V _{CC}	-	
V_{IL}	LOW Level Input Voltage	1.65 to 1.95		-	_	0.35 V _{CC}	-	0.35 V _{CC}	V
		2.30 to 5.50		-	_	0.30 V _{CC}	-	0.30 V _{CC}	
V _{OH}	HIGH Level Output Voltage	1.65	$V_{IN} = V_{IH}$ or V_{IL} ,	1.55	1.65	-	1.55	-	V
		1.80	I _{OH} = -100 μA	1.70	1.80	-	1.70	-	
		2.30		2.20	2.30	-	2.20	-	
		3.00		2.90	3.00	-	2.90	-	
		4.50		4.40	4.50	-	4.40	-	
		1.65	I _{OH} = -4 mA	1.29	1.52	-	1.29	-	
		2.30	I _{OH} = -8 mA	1.90	2.15	-	1.90	-	
		3.00	I _{OH} = -16 mA	2.40	2.80	-	2.40	-	
		3.00	I _{OH} = -24 mA	2.30	2.68	-	2.30	-	
		4.50	I _{OH} = -32 mA	3.80	4.20	-	3.80	-	
V _{OL}	LOW Level Output Voltage	1.65	$V_{IN} = V_{IH} \text{ or } V_{IL},$	-	0.00	0.10	-	0.10	V
		1.80	I _{OL} = 100 μA	-	0.00	0.10	-	0.10	
		2.30		-	0.00	0.10	-	0.10	
		3.00		-	0.00	0.10	-	0.10	
		4.50		-	0.00	0.10	-	0.10	
		1.65	I _{OL} = 4 mA	-	0.80	0.24	-	0.24	
		2.30	I _{OL} = 8 mA	-	0.10	0.30	-	0.30	
		3.00	I _{OL} = 16 mA	-	0.15	0.40	-	0.40	
		3.00	I _{OL} = 24 mA	-	0.22	0.55	-	0.55	
		4.50	I _{OL} = 32 mA	-	0.22	0.55	-	0.55	
I _{IN}	Input Leakage Current	1.65 to 5.50	V _{IN} = 5.5 V, GND	-	_	±1	-	±10	μΑ
I _{OFF}	Power Off Leakage Current	0	V _{IN} or V _{OUT} = 5.5 V	-	_	1	-	10	μΑ
I _{CC}	Quiescent Supply Current	1.65 to 5.50	V _{IN} = 5.5 V, GND	-	_	2.0	-	20	μΑ

AC ELECTRICAL CHARACTERISTICS

					Γ _A = +25°C	;	T _A = -40	to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}		1.65	C _L = 15 pF,	-	5.5	12.0	-	12.7	ns
	(Figure 4, 5)	1.80	$R_L = 1 M\Omega$	=	4.6	10.0	_	10.5	
		2.50 ±0.30		=	3.0	7.0	_	7.5	
		3.30 ±0.30		=	2.4	4.7	_	5.0	
		5.00 ±0.50		=	1.9	4.1	_	4.4	
		3.30 ±0.30	C _L = 50 pF,	_	3.0	5.2	_	5.5	
		5.00 ±0.50	$R_L = 500 \Omega$	_	2.4	4.5	_	4.8	
C _{IN}	Input Capacitance	0.00		_	4	_	_	-	pF
C _{PD}	C _{PD} Power Dissipation Capacitance	3.30		-	20	-	_	_	pF
	(Note 2) (Figure 6)	5.00		_	26	_	_	_	

C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression:
 I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CC}static).



NOTE:

C_L includes load and stray capacitance.
 Input PRR = 10 MHz, t_w = 500 ns

Figure 4. AC Test Circuit

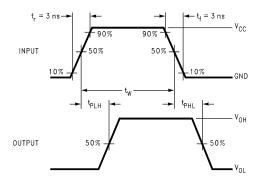
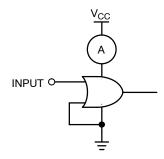


Figure 5. AC Waveforms



NOTE:

4. Input = AC Waveform; $t_r = t_f = 1.8$ ns; PRR = 10 MHz; Duty Cycle = 50%.

Figure 6. I_{CC}D Test Circuit

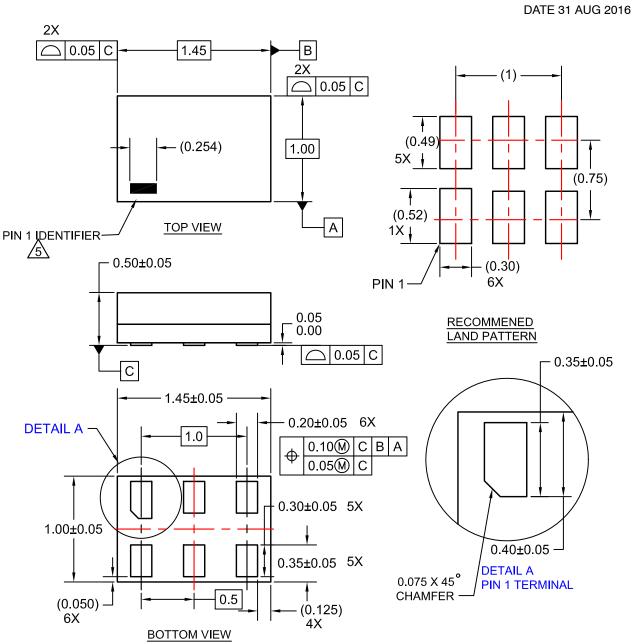
ORDERING INFORMATION

Part Number	Top Mark	Packages	Shipping [†]
NC7SZ32M5X	7Z32	SC-74A	3000 / Tape & Reel
NC7SZ32M5X-L22090	7Z32	SOT23-5	3000 / Tape & Reel
NC7SZ32P5X	Z32	SC-88A	3000 / Tape & Reel
NC7SZ32P5X-F22057	Z32	SC-88A	3000 / Tape & Reel
NC7SZ32L6X	HH	SIP6, MicroPak	5000 / Tape & Reel
NC7SZ32L6X-L22175	HH	SIP6, MicroPak	5000 / Tape & Reel
NC7SZ32FHX	HH	UDFN6, MicroPak2	5000 / Tape & Reel
NC7SZ32FHX-L22175	HH	UDFN6, MicroPak2	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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NOTES:

- 1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-2009
- 4.PIN ONE IDENTIFIER IS 2X LENGTH OF ANY
 - OTHER LINE IN THE MARK CODE LAYOUT.

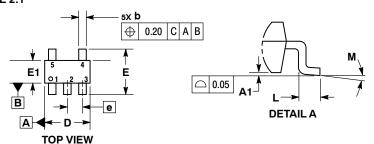
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DESCRIPTION:	SIP6 1.45X1.0		PAGE 1 OF 1

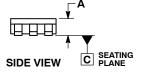
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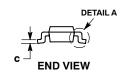




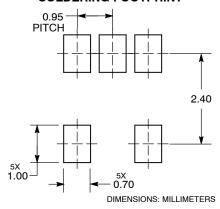
DATE 18 JAN 2018







RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- IES:
 DIMENSIONING AND TOLERANCING PER ASME
 Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE
 MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.90	1.10	
A1	0.01	0.10	
b	0.25	0.50	
С	0.10	0.26	
D	2.85	3.15	
E	2.50	3.00	
E1	1.35	1.65	
е	0.95 BSC		
L	0.20	0.60	
М	0 °	10°	

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

Μ = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SC-74A		PAGE 1 OF 1

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SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

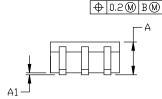
DATE 11 APR 2023

NOTES:

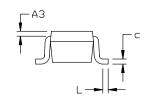
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 419A-01 DBSDLETE. NEW STANDARD 419A-02
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

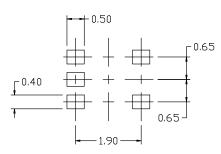
DIM	MI	LLIMETE	RS
الملتط	MIN.	N□M.	MAX.
А	0.80	0.95	1.10
A1			0.10
A3	0.20 REF		
b	0.10	0.20	0.30
С	0.10		0.25
D	1.80	2.00	2,20
Е	2.00	2.10	2.20
E1	1.15	1.25	1.35
е	0.65 BSC		
L	0.10	0.15	0.30

e Ε1 0



5X b





RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

out in the datasheet refer to the device

XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

STYLE 1	•
	EMITTER
	BASE
	COLLECTOR
5.	COLLECTOR

PIN 1. EMITTER 2

2. BASE 2

3. EMITTER 1

4. COLLECTOR

5. COLLECTOR 2/BASE 1

STYLE 6:

STYLE 2: PIN 1. ANODE 2. EMITTER 3. BASE 4. COLLECTOR CATHODE

2. EMITTER 3. BASE

4. COLLECTOR

5. COLLECTOR

STYLE 7:

PIN 1. BASE

STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1

PIN 1. CATHODE 2. COLLECTOR 3. N/C

4. BASE

STYLE 8:

STYLE 4: PIN 1. SOURCE 1 2. DRAIN 1/2 3 SOURCE 1 4. GATE 1 5. GATE 2

3. ANODE 4. ANODE

STYLE 5: PIN 1. CATHODE 2. COMMON ANODE 3. CATHODE 2 4. CATHODE 3 5. CATHODE 4

STYLE 9: Note: Please refer to datasheet for PIN 1. ANODE 2. CATHODE style callout. If style type is not called

 ANODE
 ANODE datasheet pinout or pin assignment. 5. EMITTER Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

DOCUMENT NUMBER: 98ASB42984B **DESCRIPTION:** SC-88A (SC-70-5/SOT-353) PAGE 1 OF 1

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UDFN6 1.0X1.0, 0.35P CASE 517DP ISSUE O **DATE 31 AUG 2016** 0.89 0.05 C В 1.00±0.050 Α 2X 5X 0.40 PIN 1 MIN 250uM 0.66 1 00±0 050 1X 0.45 0.05 C **TOP VIEW** 6X 0.19 2X RECOMMENDED LAND PATTERN FOR SPACE CONSTRAINED PCB 0.05 C - 0.90 -0.50±0.05 5X 0.52 SIDE VIEW 6X 0.14±0.05 (0.08)4X -0.73 **DETAIL A** 3 1X 0.57 - 0.20 6X ALTERNATIVE LAND PATTERN FOR UNIVERSAL APPLICATION (0.05)6X5X 0.30±0.05 0.60 0.10M|C|B|A(80.0).05 C 4X 0.35±0.050 **BOTTOM VIEW** NOTES: A. COMPLIES TO JEDEC MO-252 STANDARD B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009

DOCUMENT NUMBER:	98AON13593G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	UDFN6 1.0X1.0, 0.35P		PAGE 1 OF 1	

0.075X45°

CHAMFER

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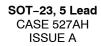
DETAIL A

PIN 1 LEAD SCALE: 2X





REFERENCE



DATE 09 JUN 2021

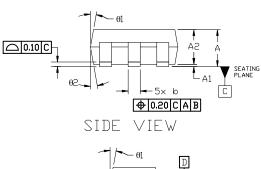
NOTES:

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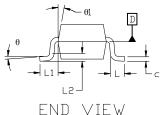
F1 F

В

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 19894
- CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS, MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED O. 25 PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM D.
- 5. DIMENSION '6' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE '6' DIMENSION AT MAXIMUM MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07mm.



TOP VIEW



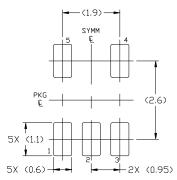
GENERIC MARKING DIAGRAM*



XXX = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	0.90	_	1.45	
A1	0.00	_	0.15	
A2	0.90	1.15	1.30	
b	0.30	_	0.50	
С	0.08	_	0.22	
D	2.90 BSC			
Ε	2.80 B2C			
E1	1.60 BSC			
е	0.95 BSC			
L	0.30	0.45	0.60	
L1	0.60 REF			
L2	0.25 REF			
θ	0°	4°	8*	
θ1	0°	10°	15°	
θ2	0*	10°	15°	



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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DESCRIPTION:	SOT-23, 5 LEAD		PAGE 1 OF 1

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